

## CHIBLINK N-Channel Enhancement Mode Power MOSFET

### Description

The ZS3080KS combines advanced trench technology to provide excellent  $R_{DS(ON)}$ , it tailored to minimize conduction loss, and provide superior switching performance. It can be used in wide variety of application.

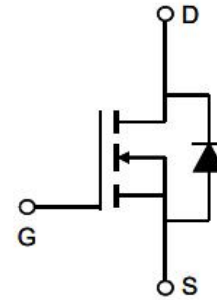
### Features

- $V_{DS}=30V$ ,  $I_D=80A$   
 $R_{DS(ON)typ.}=4.0m\Omega@V_{GS}=10V$   
 $R_{DS(ON)typ.}=6.0m\Omega@V_{GS}=4.5V$
- 100% avalanche tested
- Fast switching
- High power and current handling capability
- Termination is Lead-free and RoHS Compliant

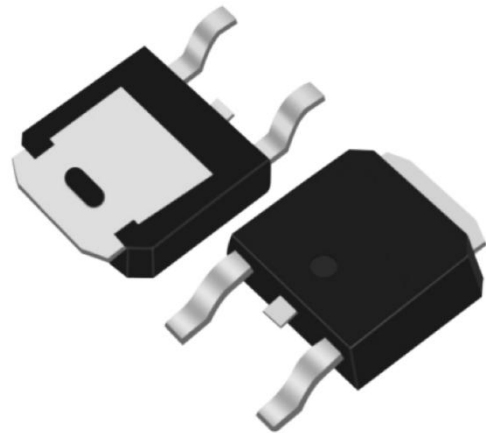


### Applications

- PWM applications
- Load switch
- Power Management



Schematic Diagram



TO252 Package

### Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D(T_C=25^\circ C)$	80	A
	$I_D(T_C=100^\circ C)$	45	
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	320	A
Maximum Power Dissipation <sup>A</sup>	$P_D$	83	W
Single pulse avalanche energy	$E_{AS}$	306	mJ
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

**Thermal Characteristic**

Thermal Resistance, Junction to Case	$R_{QJC}$	1.4	$^{\circ}C/W$
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**Electrical Characteristics ( $T_A=25^{\circ}C$  unless otherwise specified)**

Parameter	Symbol	Test conditions	MIN	TYP	MAX	UNIT
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30			V
Gate-Threshold Voltage	$V_{th(GS)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.5	2.2	V
Gate-body Leakage	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 12V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V$			1	$\mu A$
Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=30A$		4.0	5.0	m $\Omega$
		$V_{GS}=4.5V, I_D=20A$		6.0	8.0	m $\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=15V, V_{GS}=0V, F=1MHz$		1970		pF
Output Capacitance	$C_{oss}$			215		
Reverse Transfer Capacitance	$C_{rss}$			178		
<b>Switching Capacitance</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V, R_L=3\Omega, V_{GS}=10V, R_{GEN}=3\Omega$		20		nS
Turn-on Rise Time	$t_r$			15		nS
Turn-off Delay Time	$t_{d(off)}$			60		nS
Turn-off Fall Time	$t_f$			10		nS
Total Gate Charge	$Q_g$	$V_{DS}=15V, I_D=5A, V_{GS}=4.5V$		37.3		nC
Gate-Source Charge	$Q_{gs}$			5.8		nC
Gate-Drain Charge	$Q_{gd}$			7.7		nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_D=5A$			1.2	V
Diode Forward Current	$I_S$				80	A

**Notes:**

- The Power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^{\circ}C$ , using  $\leq 10s$  junction-to ambient thermal resistance.
- Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^{\circ}C$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^{\circ}C$ .
- The Static characteristics in Figures are obtained using  $< 300\mu s$  pulses, duty cycle 2% max.
- EAS condition:  $T_J=25^{\circ}C, V_{DD}=15V, V_{GS}=10V, R_G=25\Omega, L=0.5Mh$ .

### Typical Electrical and Thermal Characteristics

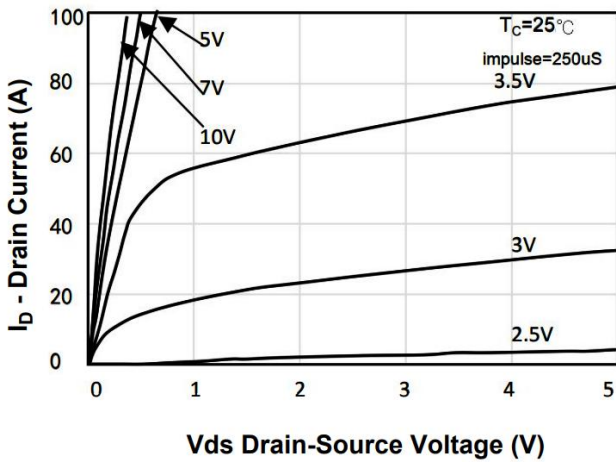


Figure 1. On-Region Characteristics

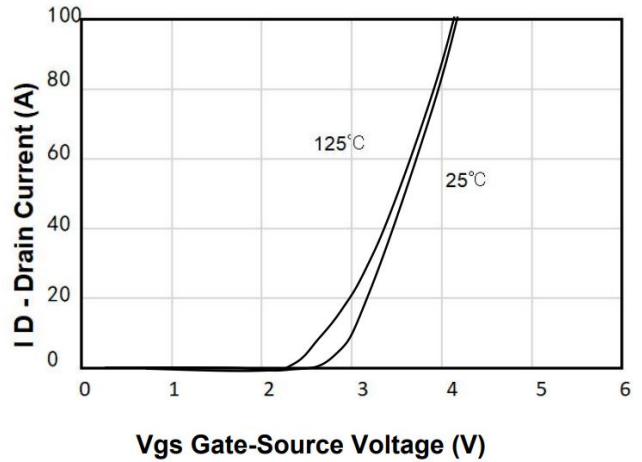


Figure 2. Transfer Characteristics

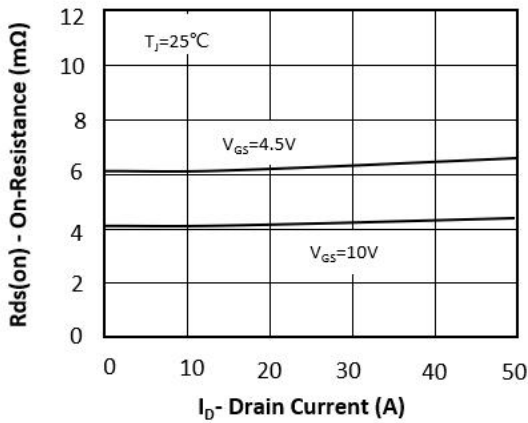


Figure 3. On-resistance vs. Drain Current

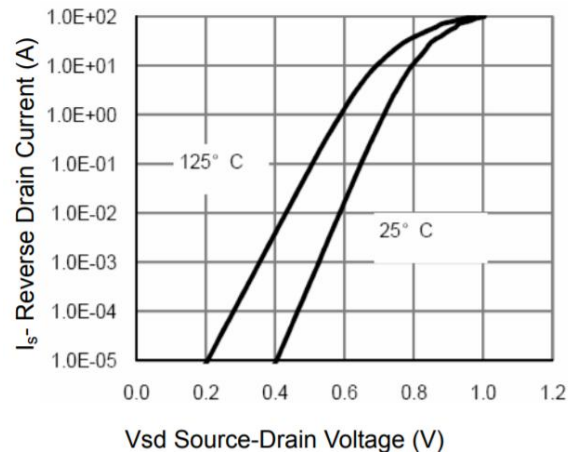


Figure 4. Body Diode Characteristics

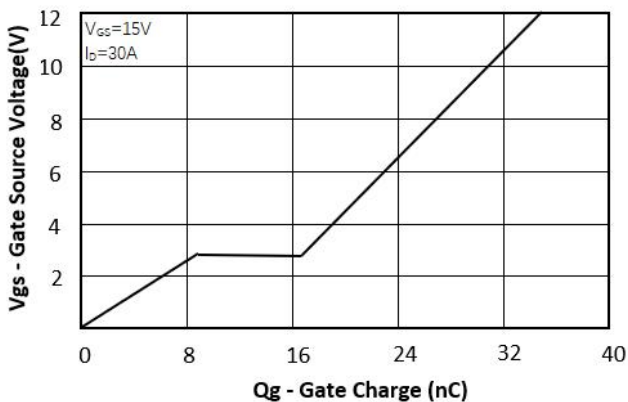


Figure 5. Gate Charge Characteristics

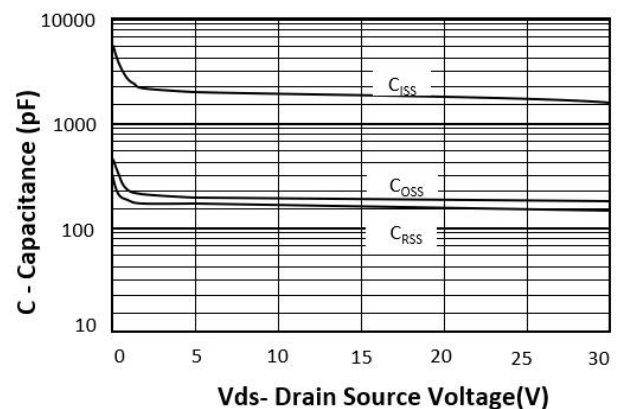
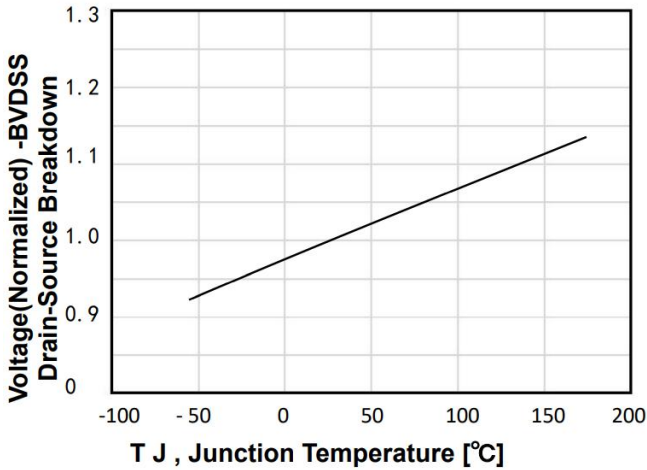
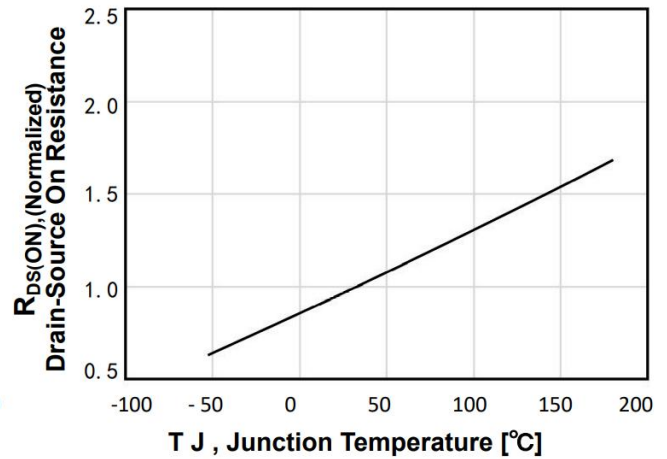


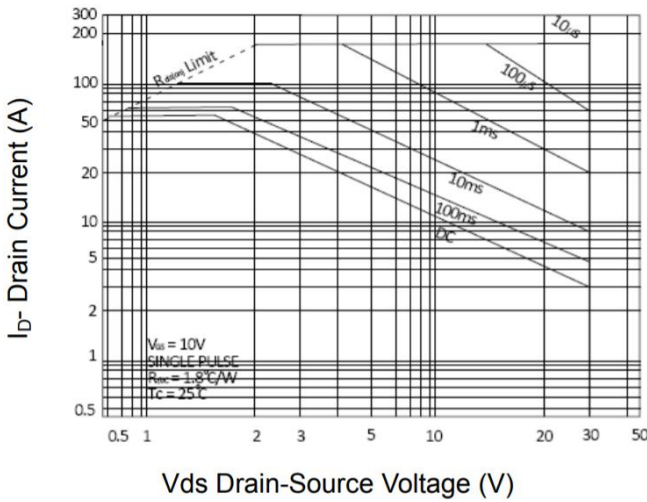
Figure 6. Capacitance Characteristics



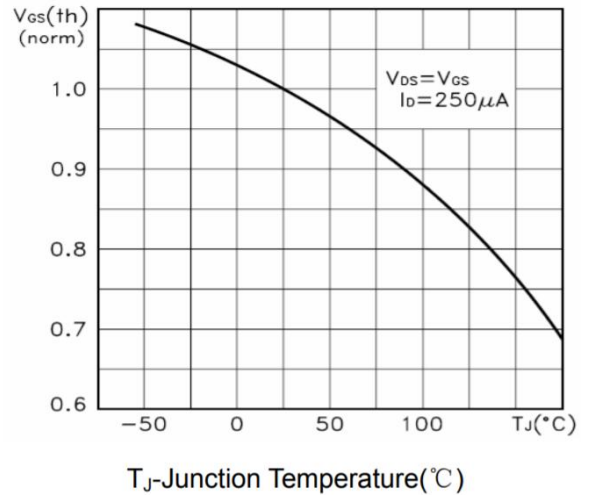
**Figure 7. Breakdown Voltage Variation vs Temperature**



**Figure 8. On-Resistance Variation vs Temperature**

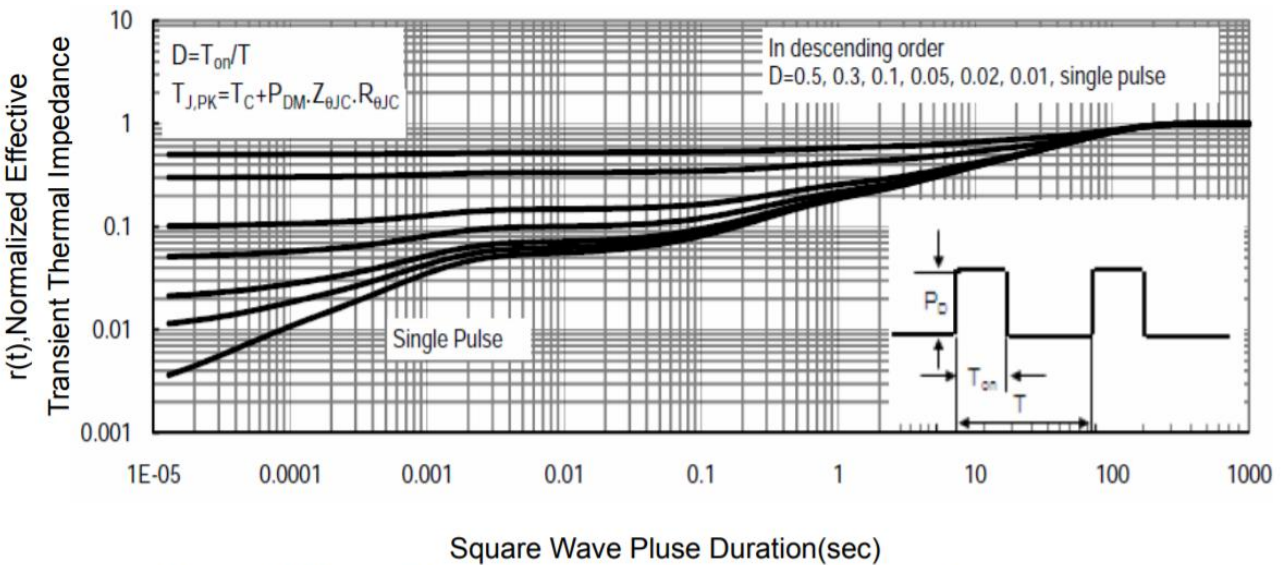


**Figure 9. Safe Operation Area**



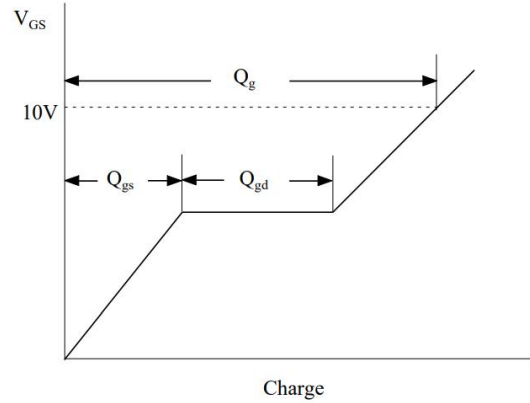
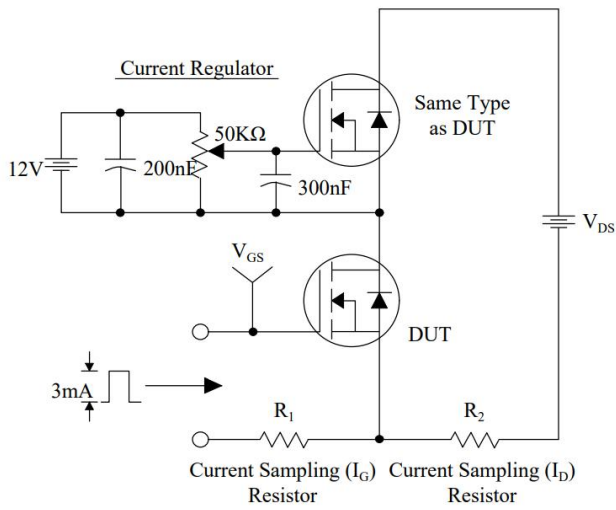
**Figure 10. Current - Junction Temperature**

Temperature

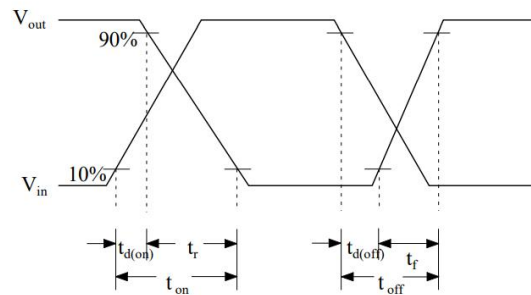
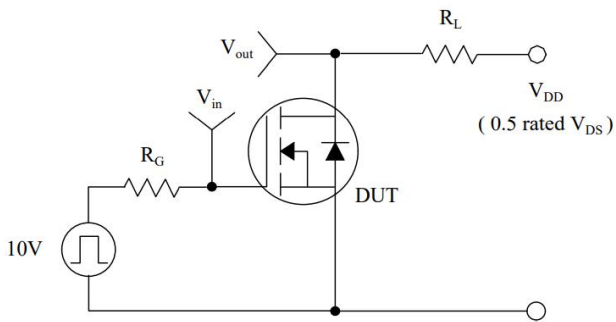


**Figure 11 Normalized Maximum Transient Thermal Impedance**

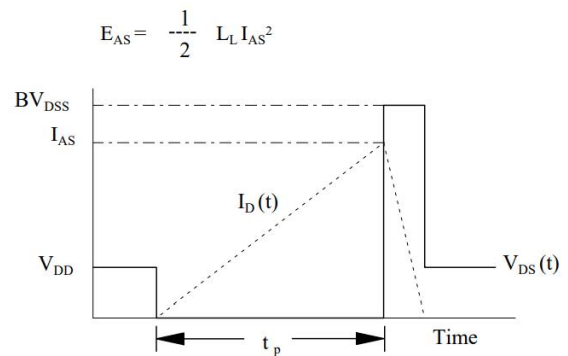
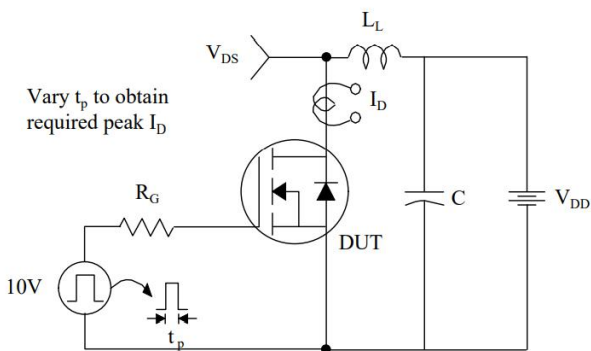
### Gate Charge Test Circuit & Waveform



### Resistive Switching Test Circuit & Waveforms



### Unclamped Inductive Switching Test Circuit & Waveforms







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